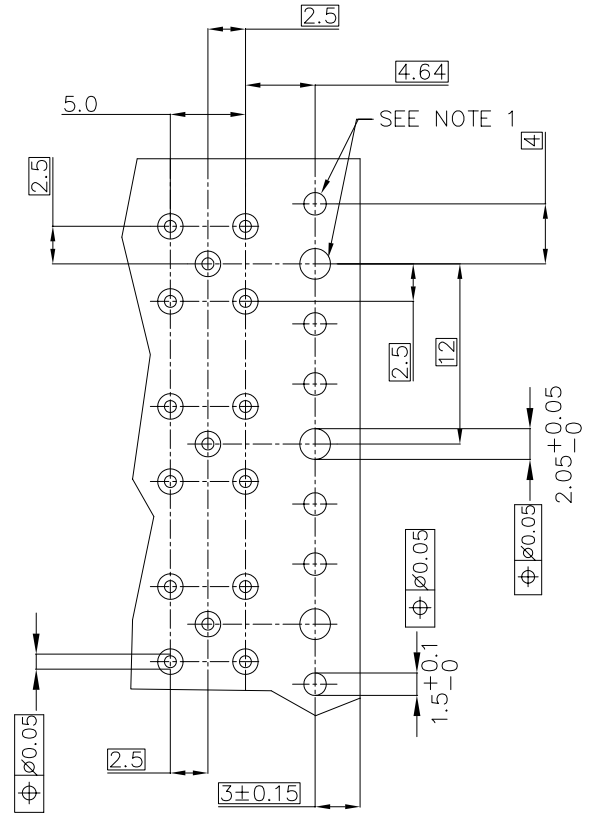
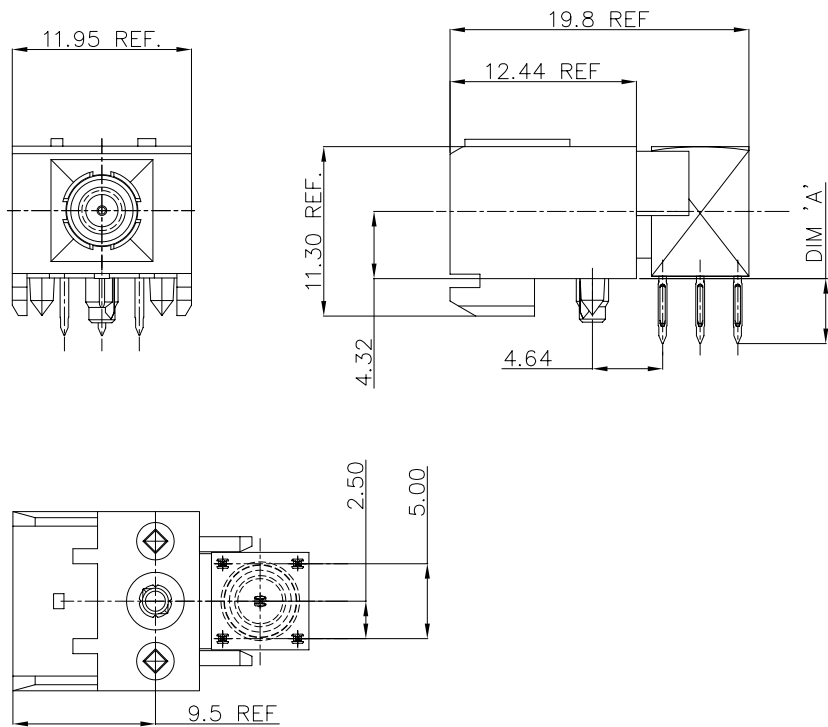


PRODUCT NO	PCB THICKNES	DIM A	NOTES
63721-101	1.6 & 2.4	4.19	3
63721-102	1.6 & 2.4	4.19	2 & 3



RECOMMENDED HOLE PATTERN,  
COMPONENT SIDE.

- ① INDICATED HOLES ARE TO BE UNPLATED
- ② COMPONENTS SUPPLIED UNASSEMBLED
- ③ ADD "LF" SUFFIX AT THE END OF PART NUMBER FOR LEAD FREE OPTION.
- ④ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
5. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD OR FOR 20 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.

PRESS FIT HOLES		
HOLE DIAMETER AFTER PLATING		0.65 - 0.80
DRILLED HOLE		0.81 - 0.86 (0.85 DRILL)
COPPER PLATING		0.025 MIN
TIN PLATING		0.005 - 0.015

mat'l. code		surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family METRAL (tm)
ltr	ecn no	dr	date	tolerances unless otherwise specified	title
A	V81487	GCR	9/03/98	angles linear xx ±.01/.3	RIGHT ANGLE COAX ASSEMBLY
B	V94348	HTB	11/16/99	xxxx ±.005/.13	
C	M06-0286	MNR	7/27/06	σ±2' xxx ±.0020/.050	
D	M07-0101	MHT	2/09/07	dr M. FETROW 7/16/98	
		enr	C. PENDLETON 9/03/98	chr C. PENDLETON 9/03/98	dwg no 63721
		app	C. PENDLETON 9/03/98		sheet 1 of 1 size A3
sheet index		revision sheet	D 1	type Product Customer Drawing	



FCIconnect.com

Copyright FCI